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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-15 (canceled)

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Claim 16 (currently amended): A method of manufacturing an electronic element, comprising the steps of:  
providing a piezoelectric substrate;  
forming electrode pads on the piezoelectric substrate;  
disposing intermediate electrodes on the electrode pads, said intermediate electrodes including base electrodes located between said electrode pads and said intermediate electrodes;  
forming bump electrodes on the intermediate electrodes;  
disposing the electronic element on a package such that said bump electrodes opposes package electrodes; and  
press-bonding said package electrodes to said bump electrodes while applying ultrasonic waves or heat;  
wherein said intermediate electrode is made of at least one of Al and an alloy including Al; and  
said base electrodes include a metallic material that ~~reduces orientation of the intermediate electrodes~~ increases the half-width of a locking curve of an X-ray diffraction peak from a (111) plane of Al in said intermediate electrode to greater than about 15 degrees.

Claim 17 (original): The method of claim 16, further comprising sealing the package airtight with a cap.

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Claim 18 (original): The method of claim 16, further comprising providing intermediate electrodes having a plurality of layers, and disposing said base electrodes between said layers of said intermediate electrodes.

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cancel*  
Claim 19 (original): The method of claim 16, wherein said bump electrodes are made of a metal having a melting point of about 450°C or more.

Claim 20 (canceled)

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